

Title (en)

INTEGRATED COMPONENT, COMPOSITE BODY CONSISTING OF AN INTEGRATED COMPONENT AND A CONDUCTIVE STRUCTURE, CHIP CARD AND METHOD FOR PRODUCING THE INTEGRATED COMPONENT

Title (de)

INTEGRIERTES BAUELEMENT, VERBUNDKÖRPER AUS EINEM INTEGRIERTEN BAUELEMENT UND EINER LEITERSTRUKTUR, CHIP-KARTE UND VERFAHREN ZUR HERSTELLUNG DES INTEGRIERTEN BAUELEMENTES

Title (fr)

ELEMENT INTEGRE, CORPS COMPOSITE CONSTITUE D'UN ELEMENT INTEGRE ET D'UNE STRUCTURE CONDUCTRICE, CARTE A PUCE ET PROCEDE DE PRODUCTION DE L'ELEMENT INTEGRE

Publication

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Application

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Abstract (en)

[origin: WO0007239A1] The invention relates to an integrated component (35) with at least one contact element (20) for connecting the component (35) to a fixing means (90). According to the invention, the component (35) is embodied in such a way that the contact element (20) is disposed in an edge area of the integrated component (35) and the contact element (20) has at least one contact surface (22) which is inclined in relation to a main surface of the component (35). The invention also relates to a method for the production of said component.

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IPC 8 full level

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